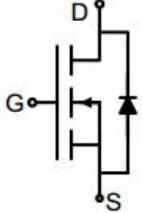
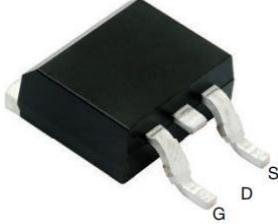


N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The GT023N10M uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 100V ● I_D (at $V_{GS} = 10V$) 226A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 2.7mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-263</p>
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Ordering Information

Device	Package	Marking	Packaging
GT023N10M	TO-263	GT023N10	800pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Continuous Drain Current	I_D	226	A
Pulsed Drain Current (note1)	I_{DM}	904	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	250	W
Single pulse avalanche energy (note2)	E_{AS}	600	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 175	°C

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62	°C/W
Maximum Junction-to-Case	R_{thJC}	0.5	°C/W

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 60\text{A}$	--	2.2	2.7	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{GS}} = 5\text{V}, I_D = 80\text{A}$	--	129	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 50\text{V}, f = 0.3\text{MHz}$	--	8148	--	pF
Output Capacitance	C_{oss}		--	3042	--	
Reverse Transfer Capacitance	C_{rss}		--	25	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 50\text{V}, I_D = 80\text{A}, V_{\text{GS}} = 10\text{V}$	--	121	--	nC
Gate-Source Charge	Q_{gs}		--	36	--	
Gate-Drain Charge	Q_{gd}		--	26	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50\text{V}, I_D = 80\text{A}, R_G = 5\Omega$	--	24	--	ns
Turn-on Rise Time	t_r		--	30	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	94	--	
Turn-off Fall Time	t_f		--	74	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	226	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 80\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 80\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	297	--	nC
Reverse Recovery Time	T_{rr}		--	94	--	ns

Notes

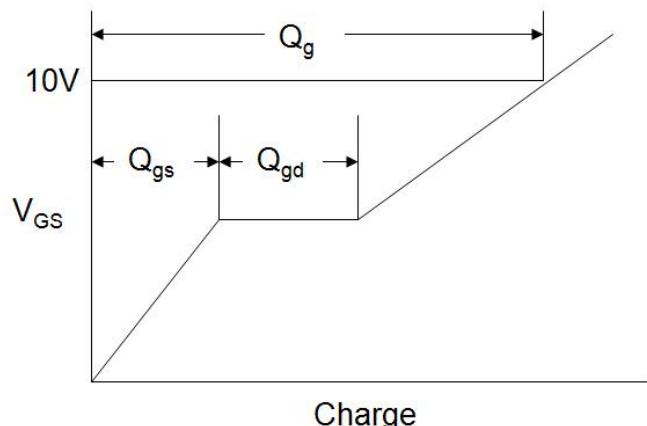
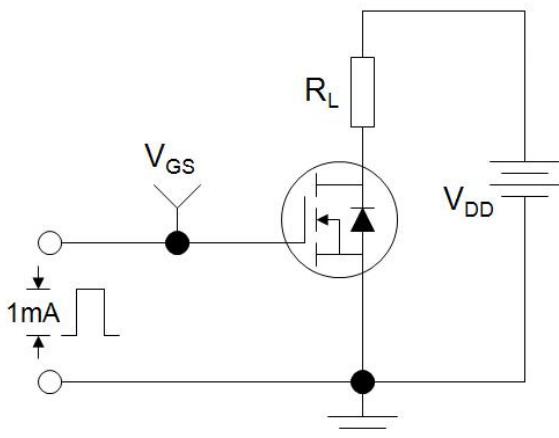
1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$

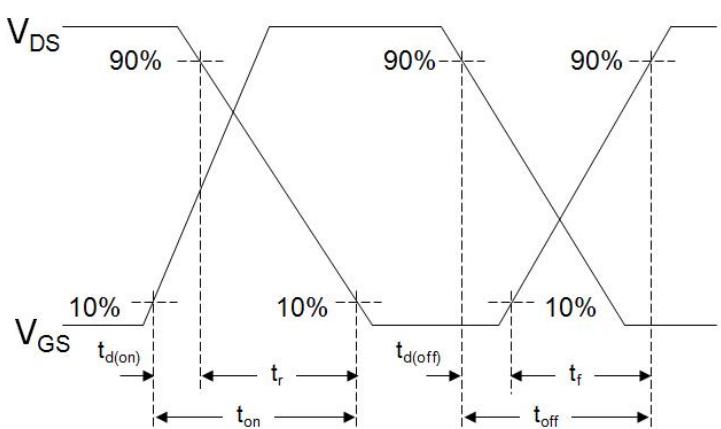
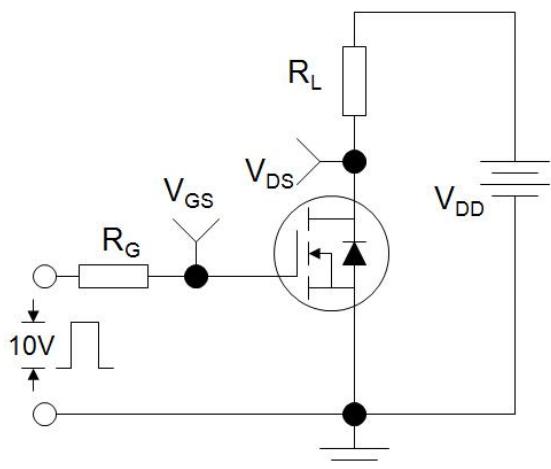
The table shows the minimum avalanche energy, which is 1600mJ when the device is tested until failure

3. Identical low side and high side switch with identical R_G

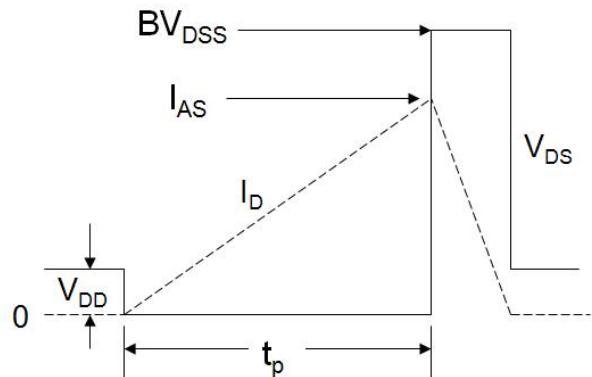
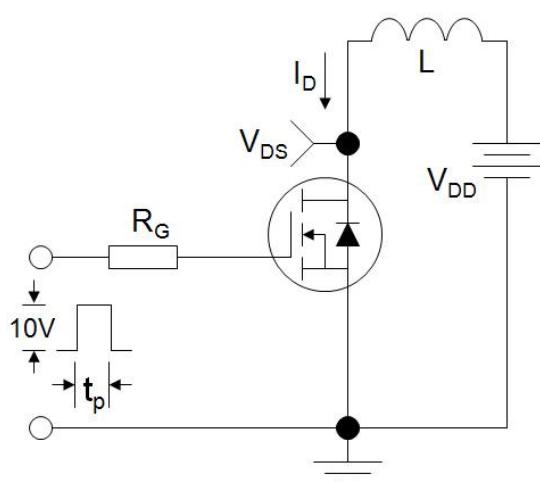
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

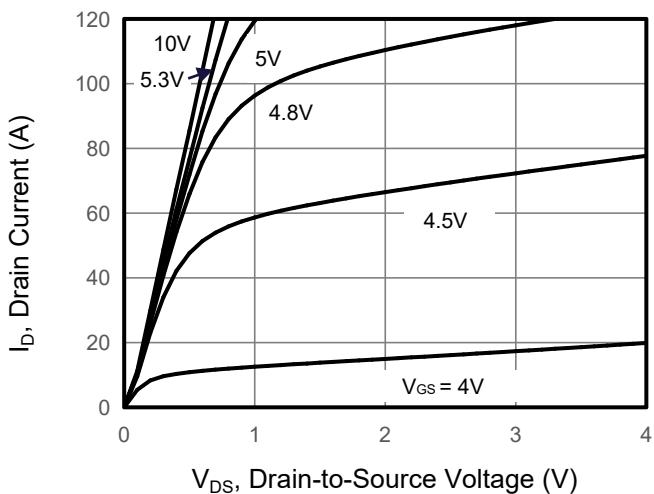


Figure 2. Transfer Characteristics

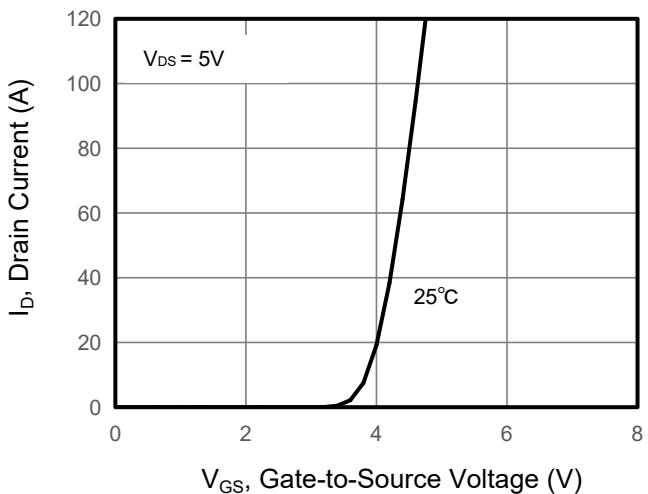


Figure 3. Drain Source On Resistance

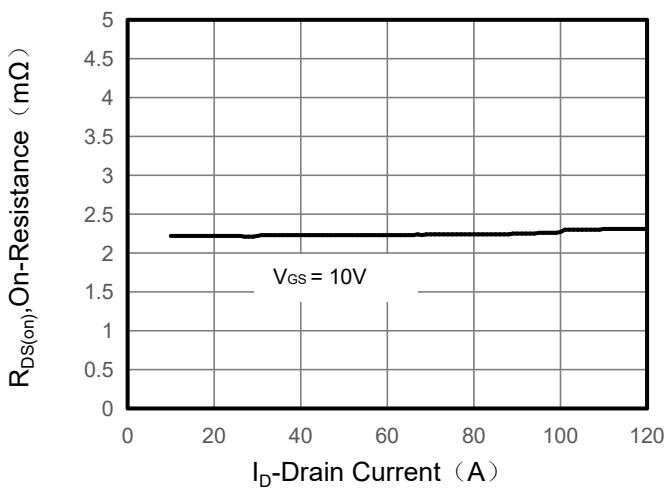


Figure 4. Gate Charge

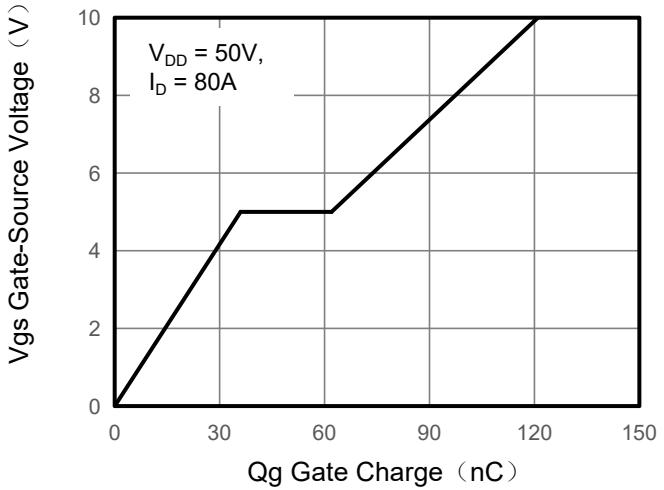


Figure 5. Capacitance

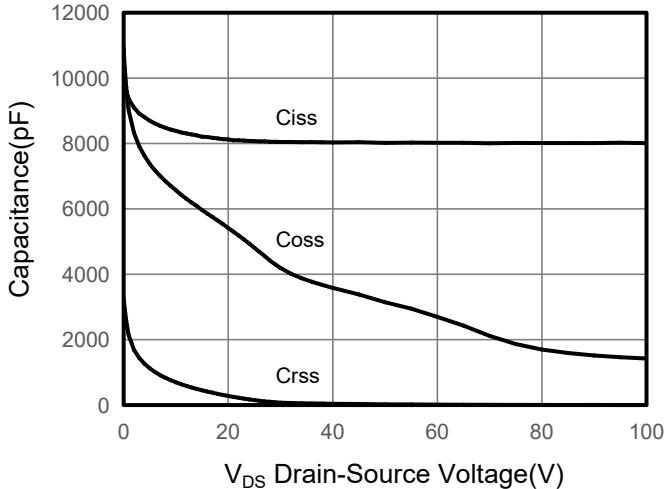
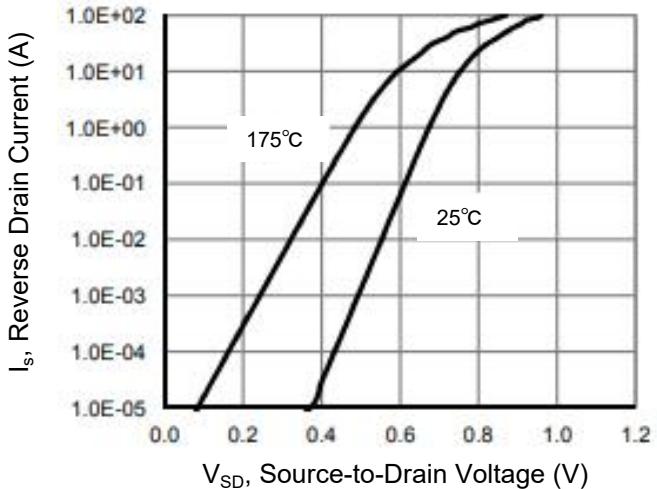


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

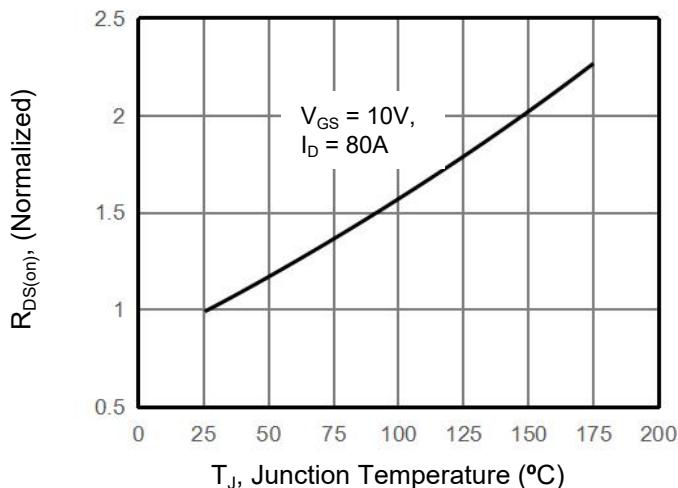


Figure 8. Safe Operation Area

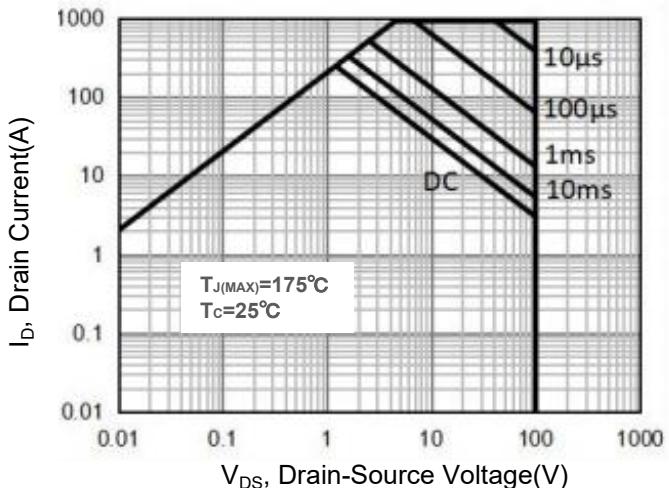
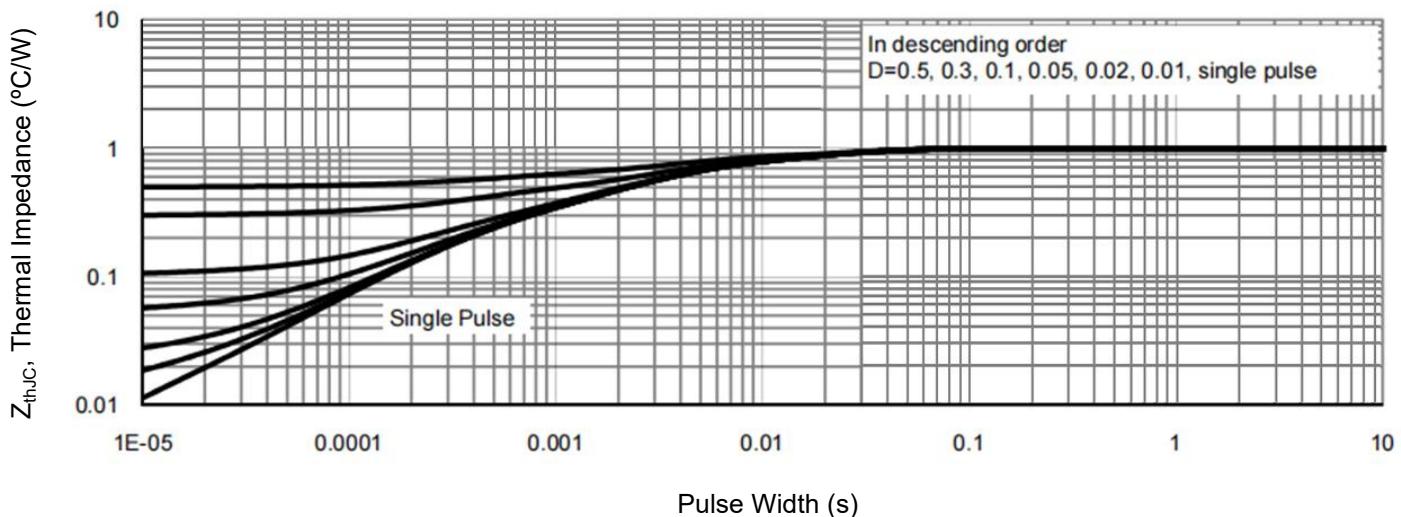
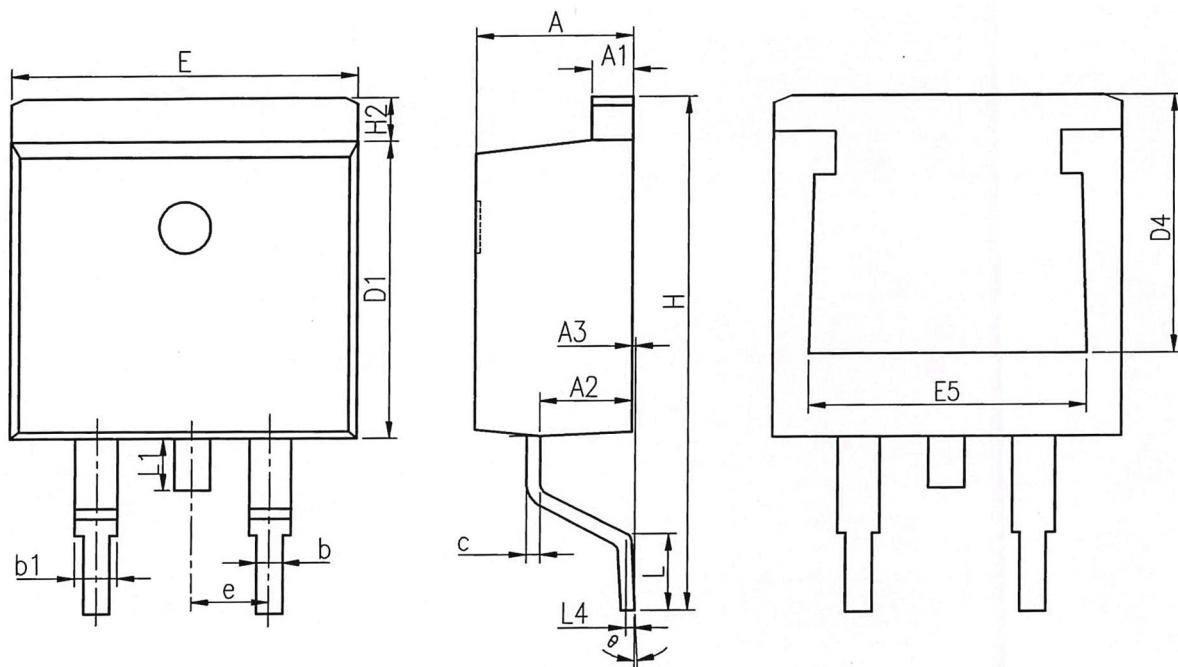


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-263 Package Information



COMMON DIMENSIONS

SYMBOL	MM			SYMBOL	MM		
	MIN	NOM	MAX		MIN	NOM	MAX
A	4.37	4.57	4.77	E	9.86	10.16	10.36
A1	1.22	1.27	1.42	E5	7.06	-	-
A2	2.49	2.69	2.89	e	2.54 BSC		
A3	0.00	0.13	0.25	H	14.70	15.10	15.50
b	0.70	0.81	0.96	H2	1.07	1.27	1.47
b1	1.17	1.27	1.47	L	2.00	2.30	2.60
c	0.30	0.38	0.53	L1	1.40	1.55	1.70
D1	8.50	8.70	8.90	L4	0.25 BSC		
D4	6.60	-	-	θ	0°	5°	9°